



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD60R210CFD7		<b>Issued</b>		9. January 2019		
<b>MA#</b>		MA002256712						
<b>Package</b>		PG-TO252-3-341		<b>Weight*</b>		388.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.709	0.95	0.95	9536	9536
leadframe	inorganic material	phosphorus	7723-14-0	0.075	0.02		192	
	non noble metal	iron	7439-89-6	0.248	0.06		639	
	non noble metal	copper	7440-50-8	248.124	63.79	63.87	637876	638707
	non noble metal	aluminium	7429-90-5	0.862	0.22	0.22	2217	2217
wire	non noble metal	aluminium	7429-90-5	0.862	0.22	0.22	2217	2217
encapsulation	organic material	carbon black	1333-86-4	0.385	0.10		991	
	plastics	epoxy resin	-	11.692	3.01		30058	
	inorganic material	silicondioxide	60676-86-0	116.408	29.93	33.04	299262	330311
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9615	9615
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1308	1308
solder	non noble metal	tin	7440-31-5	0.065	0.02		166	
	noble metal	silver	7440-22-4	0.081	0.02		208	
	non noble metal	lead	7439-92-1	3.086	0.79	0.83	7932	8306
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com